

SPECIFICATIONS CLA50CW2C

OUTLINES DIMENSIONS

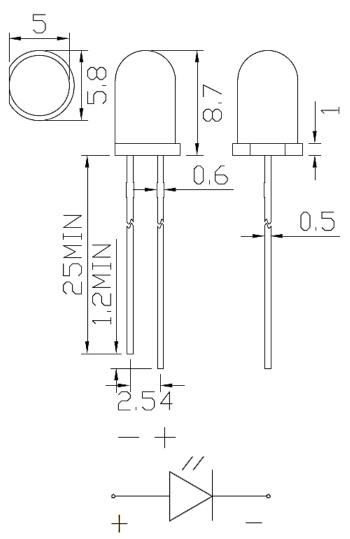
Description

- *Round Type
- *T1-3/4 (5mm) Diameter
- *Lens Color: Water Clear
- *With Flange

Features

*Emitting Color: Cool White *High Luminous Intensity

*Technology: InGaN



Notes:

- 1. All Dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.25mm (0.01") unless otherwise noted.
- 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CLA50CW2C	InGaN	White	Water Clear	15°



ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com



ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit
Power Dissipation	Pb	100	mW
Pulse Current Forward Current	lFP	60	mA
Continuous Forward Current	lF	30	mA
Reverse Voltage	VR	5	V
Operating Temperature Range	Topr	-25~+85	°C
Storage Temperature Range	Тѕтс	-30~+85	°C
IFP = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec			

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Parameter	Symbol Test	Toot Condition	Value			Linit
farameter		Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	I⊧ = 20mA	15000	17500	-	mcd
Forward Voltage	VF	I⊧ = 20mA	-	3.2	3.4	V
Reverse Leakage Current	lR	V _R = 5V	-	-	5	μΑ
Viewing Angle	201/2	I _F = 20mA	-	15	1	deg
Correlated Color Temperature	ССТ	I _F = 20mA	6000	1	6500	K
Chromacticity Coordinates	Х	I₅ = 20mA	-	0.31	-	-
	Y	IF - ZUITIA	-	0.32	-	-

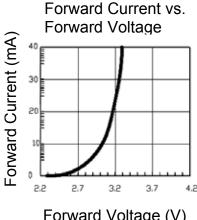
^{*}Tolerance of viewing angle: -10 / +5 deg.



ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com



OPTICAL CHARACTERISTIC CURVES



Forward Current vs. Relative Luminous Intensity Luminous Intensity Ratio 3.0 E 2.5 2.0 1.5 1.0 0.5

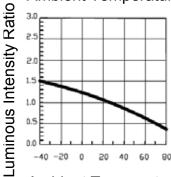
Forward Current vs. Ambient Temperature Forward Current (mA) 10

Forward Voltage (V)

Forward Current (mA)

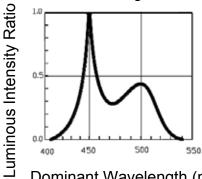
Ambient Temperature (°C)

Relative Luminous Intensity vs. **Ambient Temperature**



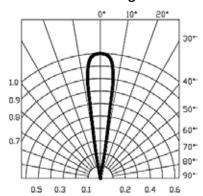
Ambient Temperature (°C)

Relative Luminous Intensity vs. Main Wavelength



Dominant Wavelength (nm)

Radiation Diagram





SOLDERING CONDITIONS – LAMP TYPE LED

- * Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- * Recommended soldering conditions

<u> </u>			
Dip Soldering			
Pre-Heat	100 °C Max		
Pre-Heat Time	60 Second Max		
Solder Bath Temperature	260 °C Max		
Dippng Time	5 Second Max		
Dipping Position	No lower than 3mm from the base of the epoxy		

Hand Soldering				
	3mm Series	Others		
Temperature Soldering Time Position	300 °C Max 3 Second Max No closer than 3mm from the base of the epoxy	350 °C Max 3 Second Max No closer than 3mm from the base of the epoxy		

- * Do not apply any stress to the lead. Particularly when heated.
- * The LED must not be repositioned after soldering.
- * After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- * Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- * When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- * Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.

